

## N-Channel Enhancement Mode MOSFET

### 1. Product Information

#### Features

Fast Switching Capability  
Avalanche Energy Specified  
Improved dv/dt Capability, High Ruggedness

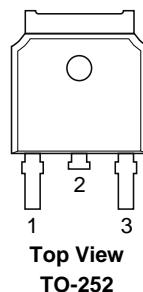
#### Pin Description

Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

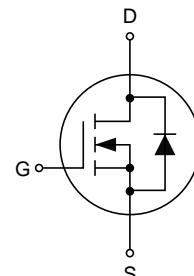
#### Applications

Uninterruptible Power Supply  
Power Factor Correction

#### Simplified Outline



#### Symbol



#### Quick reference

$V_{DS} = 200 \text{ V}$   
 $I_D = 5 \text{ A}$   
 $R_{DS(ON)} \leq 600 \text{ m}\Omega @ V_{GS}=10 \text{ V}$  (Type: 530 mΩ)

#### Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape Width	Quantity	
KJ5N20KH	TO-252	KJ5N20KH XXXXYY	XXXXYY: Date Code	-	-	2500

### 2. Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise noted)

Symbol	Parameter	Values	Unit
$V_{DS}$	Drain-Source Voltage	200	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current Continuous	5	A
$I_{DM}$	Pulsed Drain Current	20	A
$I_{AR}$	Repetitive Avalanche Current	3	A
$E_{AS}$	Single Pulse Avalanche Energy	45	mJ
$E_{AR}$	Repetitive Avalanche Energy	3.2	mJ
$P_D$	Power Dissipation	46	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55~150	°C
$R_{thJA}$	Thermal Resistance, Junction-to-Case	60	°C/W
$R_{thJC}$	Thermal Resistance, Junction-to-Ambient	2.7	°C/W

### 3. Electrical Characteristics ( $T_C=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=250 \mu\text{A}$	200	220	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=200 \text{ V}, V_{\text{GS}}=0 \text{ V}$	-	-	5	$\mu\text{A}$
		$V_{\text{DS}}=160 \text{ V}, T_C=125^\circ\text{C}$	-	-	100	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{DS}}=0 \text{ V}, V_{\text{GS}}=\pm 20 \text{ V}$	-	-	$\pm 100$	nA
$V_{\text{GS(th)}}$	Gate-Source Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250 \mu\text{A}$	2.5	3.1	4.0	V
$R_{\text{DS(on)}}$	Drain-Source On-Resistance <sup>(note 3)</sup>	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=2.5 \text{ A}$	-	530	600	$\text{m}\Omega$
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0 \text{ V}, V_{\text{DS}}=25 \text{ V}, f=1.0 \text{ MHz}$	-	228	-	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		-	48	-	
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	17	-	
$Q_g$	Total Gate Charge	$V_{\text{DS}}=160 \text{ V}, V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=5 \text{ A}$	-	18	-	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		-	1.5	-	
$Q_{\text{gd}}$	Gate-Drain Charge		-	9.5	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=100 \text{ V}, I_{\text{D}}=5 \text{ A}, R_{\text{G}}=25 \Omega$	-	10	-	$\text{ns}$
$t_r$	Turn-on Rise Time		-	19	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	43	-	
$t_f$	Turn-off Fall Time		-	32	-	
$I_s$	Maximum Continuous Drain-Source Diode Forward Current	-	-	5	A	
$I_{\text{SM}}$	Maximum Pulsed Drain-Source Diode Forward Current	-	-	20	A	
$V_{\text{SD}}$	Diode Forward Voltage	$T_C=25^\circ\text{C}, V_{\text{GS}}=0 \text{ V}, I_s=5 \text{ A}$	-	-	1.4	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{GS}}=0 \text{ V}, I_s=5 \text{ A}, dI/dt=100 \text{ A}/\mu\text{s}$	-	160	-	$\text{ns}$
$Q_{\text{rr}}$	Reverse Recovery Charge		-	1.5	-	

Note:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2 OZ copper.
2. The EAs data shows Max. rating.  $I_{\text{AS}}=3 \text{ A}, V_{\text{DD}}=50 \text{ V}, R_{\text{G}}=25 \Omega$ , Starting  $T_J=25^\circ\text{C}$
3. Pulse Test: Pulse width  $\leq 300 \mu\text{s}$ , Duty cycle  $\leq 1\%$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

## 4. Typical Characteristics

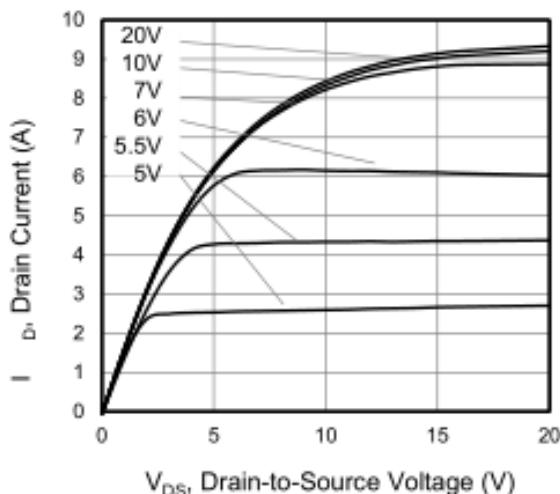


Figure 1: Output Characteristics ( $T_J=25^\circ\text{C}$ )

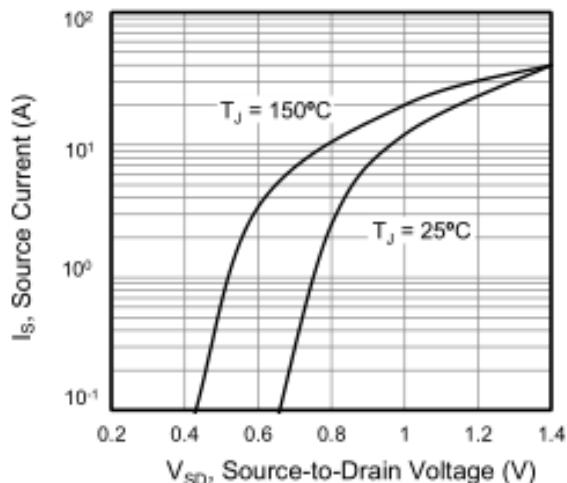


Figure 2: Body Diode Forward Voltage

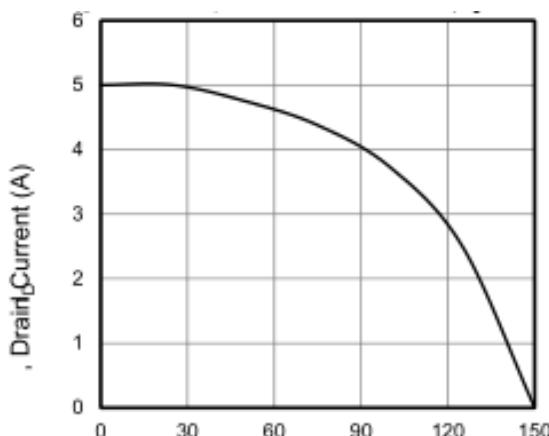


Figure 3: Drain Current vs. Temperature

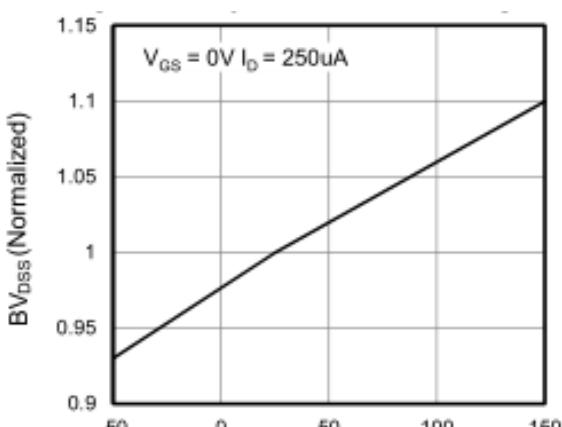


Figure 4: Body Diode Characteristics

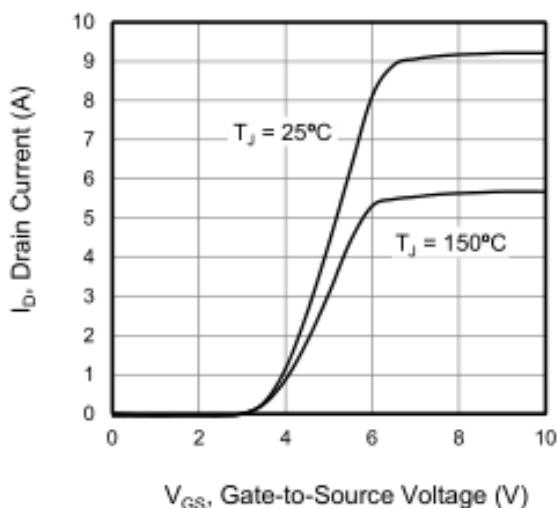


Figure 5: Transfer Characteristics

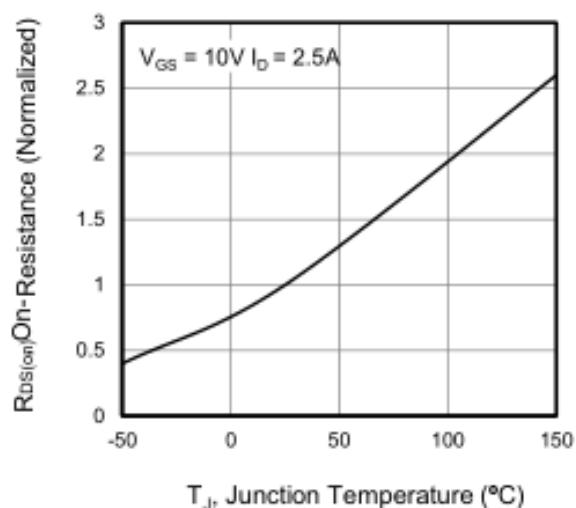


Figure 6: On-resistance vs. Temperature

## 4. Typical Characteristics (Cont.)

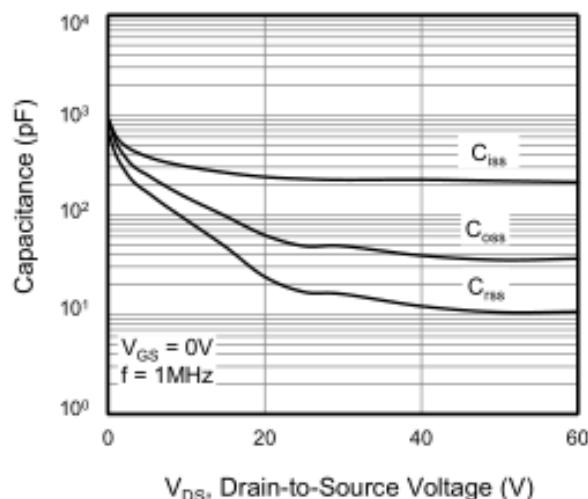


Figure 7: Capacitance

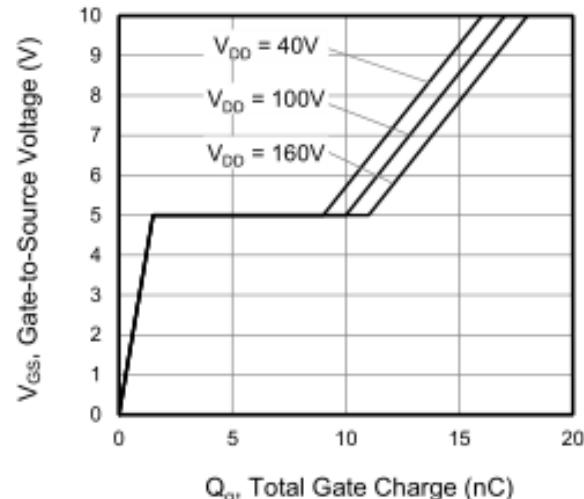


Figure 8: Gate Charge

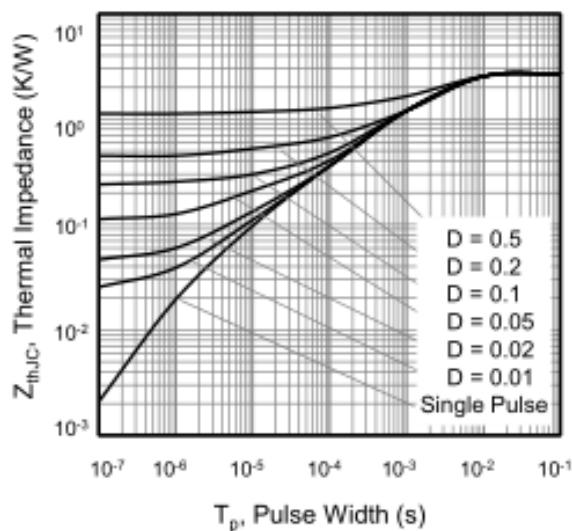
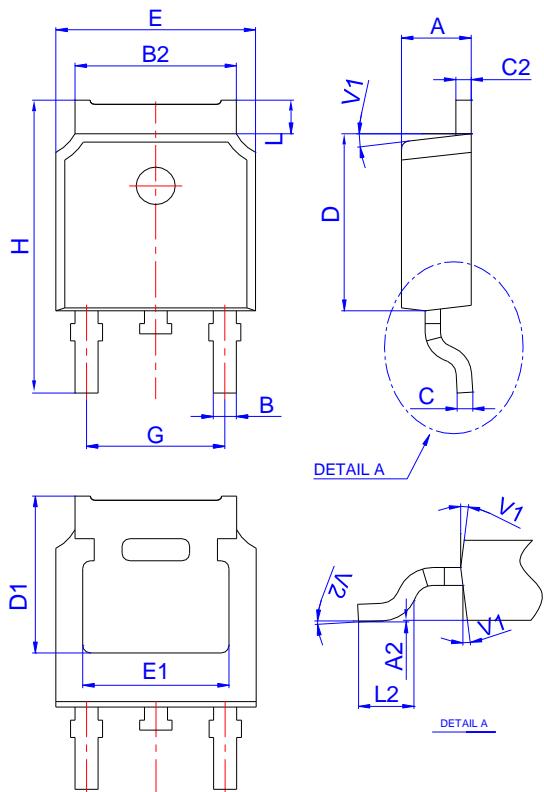


Figure 9: Transient Thermal Impedance

## 5. Package Mechanical Data

### TO-252 Package



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

